

# EREC0806E

## Hyperfast soft recovery rectifier



### Product features

- Plastic package UL 94V-0
- Low reverse leakage current
- Hyperfast recovery time and soft recovery characteristics
- Low recovery loss

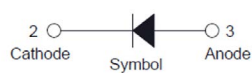
### Mechanical data

- Case: TO-263 molded plastic over passivated junction
- Terminals: Tin plated
- Weight: 1.55 grams typical

### Package diagram/size and schematic



TO-263



1	No connection
2,4	Cathode
3	Anode

### Applications

- Switching mode power supplies
- Inverters
- Freewheeling diodes
- DC/DC converters
- Other power switching applications

### Environmental compliance and general specifications



### Ordering part number

E	R	E	C	08	06	E
1	2	3	4	5	6	7

1	E=Eaton
2	R=Rectifier
3	E=Epitaxial process
4	C=Hyperfast
5	08= $I_T(AV)$ : 8 A
6	06= $V_{RRM}$ : 600 V
7	E=Package: TO-263

### Absolute maximum ratings

(Rating at +25 °C ambient temperature unless otherwise specified)

Parameter	Symbol	Value	Unit
Maximum repetitive peak reverse voltage	$V_{RRM}$	600	V
Maximum RMS voltage	$V_{RMS}$	420	V
Maximum DC blocking voltage	$V_{DC}$	600	V
Average forward current at $T_{mb} \leq 130$ °C	$I_{F(AV)}$	8	A
Peak forward surge current: 10 ms single half sinewave superimposed on rated load	$I_{FSM}$	90	A
Peak forward surge current: 8.3 ms single half sinewave superimposed on rated load		100	
Operating junction and storage temperature range	$T_j, T_{stg}$	-55 to +150	°C

### Electrical characteristics

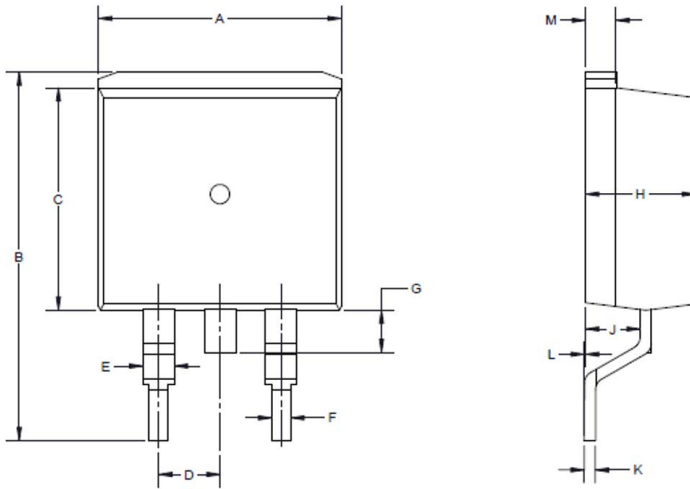
(Rating at +25 °C ambient temperature unless otherwise specified)

Parameter	Test condition	Symbol	Minimum	Typical	Maximum	Unit
Forward voltage @IF=8 A	$T_j=25$ °C	$V_F$	-	-	3.4	V
Reverse current at rated DC blocking voltage	$T_j=25$ °C	$I_R$	-	-	5	µA
	$T_j=125$ °C		-	-	200	
Reverse recovery time	IF=1 A, VR=30 V, di/dt=200 A/µs, $T_j=25$ °C	$t_{rr}$	-	12	18	ns
Peak reverse recovery current	IF=8 A, VR=200 V, di/dt=200 A/µs, $T_j=25$ °C	$I_{RM}$	-	-	2.2	A
	IF=8 A, VR=200 V, di/dt=200 A/µs, $T_j=125$ °C		-	-	6	
Reverse recovery charge	IF=8 A, VR=200 V, di/dt=200 A/µs, $T_j=25$ °C	$Q_{rr}$	-	17	-	nC
	IF=8 A, VR=200 V, di/dt=200 A/µs, $T_j=125$ °C		-	90	-	

### Thermal resistances

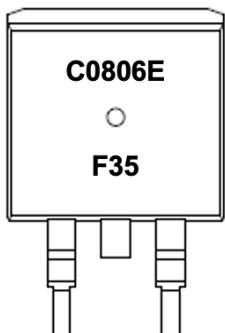
Symbol	Parameter	Minimum	Typical	Maximum	Unit
$R_{th(j-a)}$	Thermal resistance from junction to ambient	-	60	-	°C/W
$R_{th(j-mb)}$	Thermal resistance from junction to mounting base	-	-	2.5	°C/W

**Mechanical drawing- mm**



Dimension	Minimum	Typical	Maximum
A	9.9	-	10.2
B	14.7	-	15.8
C	8.8	-	9.6
D	-	2.54	-
E	1.2	-	1.4
F	0.75	-	0.85
G	-	-	1.75
H	4.4	-	4.7
J	2.3	-	2.7
K	0.38	-	0.55
L	0	0.1	0.25
M	1.17	-	1.37

**Marking**



**Product information**

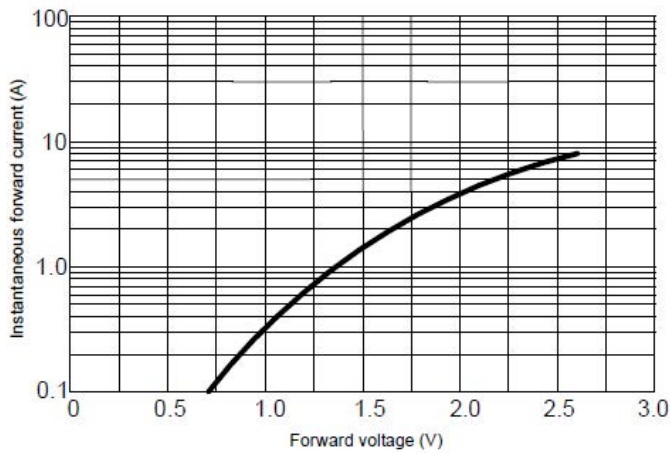
C	Hyperfast
08	$I_{F(AV)}$ : 8 A
06	$V_{RRM}$ : 600 V
E	Package: TO-263
F35	Date code

**Packaging information**

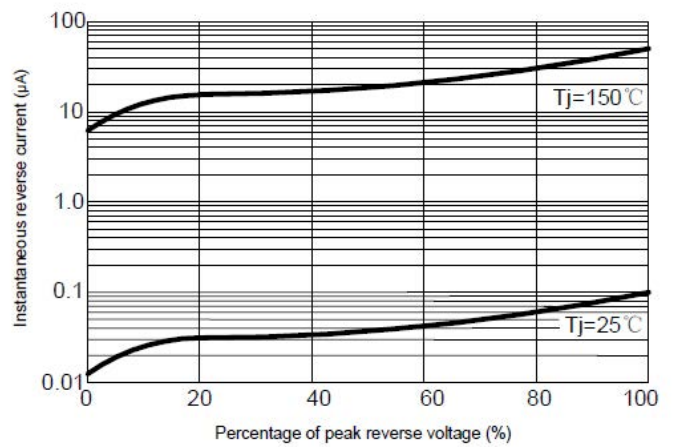
Outline	Unit weight (g/PCS) typical	Tube (pcs)	Per carton (pcs)
TUBE	1.55	50	5,000

**Typical characteristics**

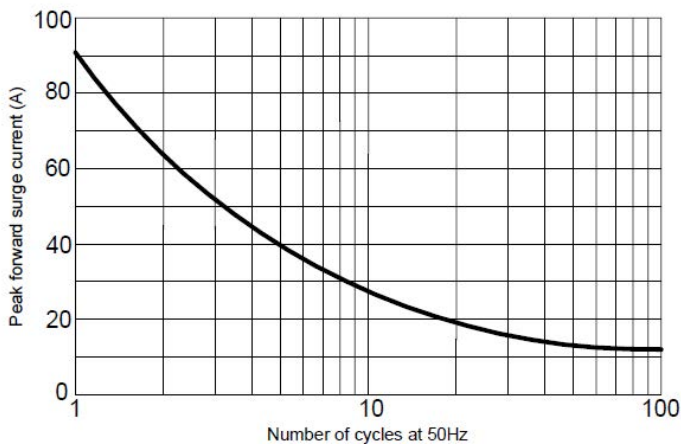
**Typical forward characteristics (+25 °C)**



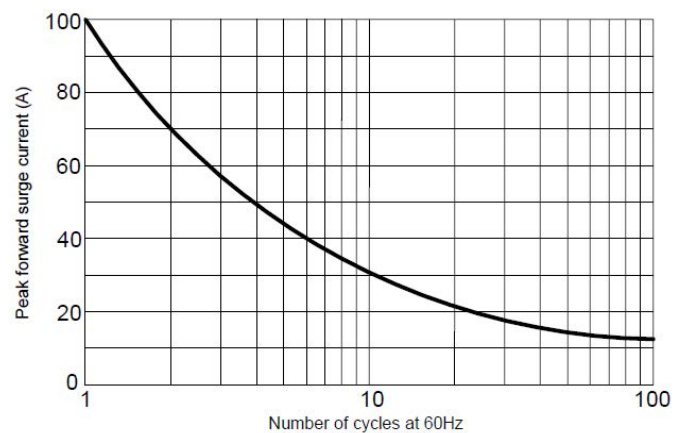
**Typical reverse characteristics**



**Maximum non-repetitive peak forward surge current (10 ms single half sine-wave) (+25 °C)**

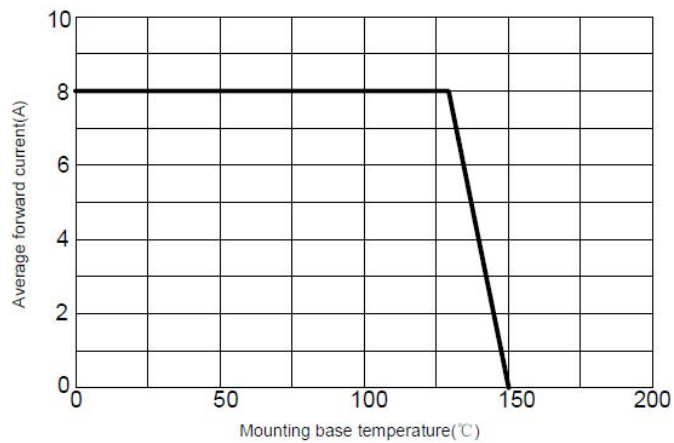


**Maximum non-repetitive peak forward surge current (8.3 ms single half sine-wave) (+25 °C)**

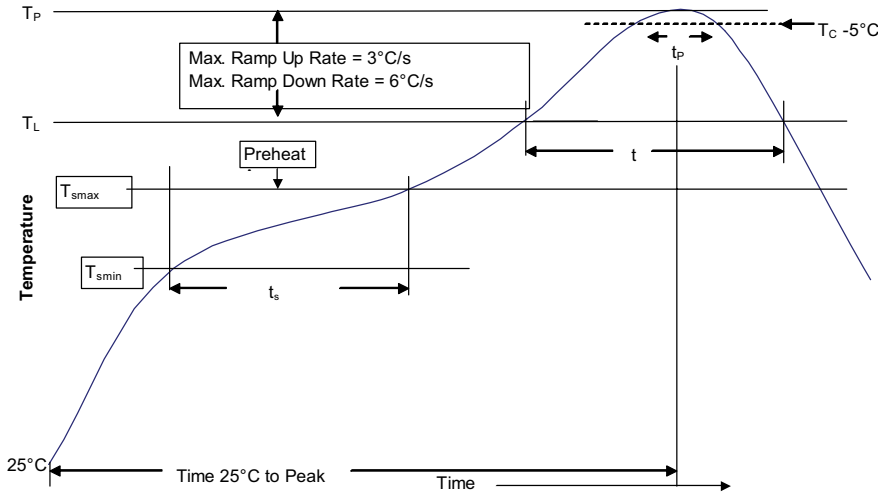


**Typical characteristics**

**Forward current derating curve**



### Solder reflow profile



**Table 1 - Standard SnPb solder ( $T_C$ )**

Package thickness	Volume $mm^3$ <350	Volume $mm^3$ $\geq$ 350
<2.5 mm	235 °C	220 °C
$\geq$ 2.5 mm	220 °C	220 °C

**Table 2 - Lead (Pb) free solder ( $T_C$ )**

Package thickness	Volume $mm^3$ <350	Volume $mm^3$ 350 - 2000	Volume $mm^3$ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 – 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

### Reference J-STD-020

Profile feature	Standard SnPb solder	Lead (Pb) free solder
Preheat and soak	<ul style="list-style-type: none"> <li>Temperature min. (<math>T_{smin}</math>)</li> <li>Temperature max. (<math>T_{smax}</math>)</li> <li>Time (<math>T_{smin}</math> to <math>T_{smax}</math>) (<math>t_s</math>)</li> </ul>	<ul style="list-style-type: none"> <li>100 °C</li> <li>150 °C</li> <li>60-120 seconds</li> </ul>
Ramp up rate $T_L$ to $T_p$	3 °C/ second max.	3 °C/ second max.
Liquidous temperature ( $T_L$ ) Time ( $t_L$ ) maintained above $T_L$	<ul style="list-style-type: none"> <li>183 °C</li> <li>60-150 seconds</li> </ul>	<ul style="list-style-type: none"> <li>217 °C</li> <li>60-150 seconds</li> </ul>
Peak package body temperature ( $T_p$ )*	Table 1	Table 2
Time ( $t_p$ )* within 5 °C of the specified classification temperature ( $T_C$ )	20 seconds*	30 seconds*
Ramp-down rate ( $T_p$ to $T_L$ )	6 °C/ second max.	6 °C/ second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

\* Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.

### Manual solder

Use a 20 W soldering iron with tip diameter of 1.0 mm maximum.  
+350 °C, 4-5 seconds maximum, generally manual, hand soldering is not recommended.

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